



Moisture Sensitivity Level 3 Handling Guidelines

Rev. 00

1. Packages and Devices

Ancora follows JEDEC standards for moisture classifications.

2. MSL 3 Handling at PCB Assembly

Packages listed above are moisture sensitive and need to be handled within proper MSL 3 guidelines to avoid damage from moisture absorption and exposure to solder reflow temperatures that can result in yield and reliability degradation.

- a. Devices are baked and dry-packed before shipment. The packing uses a Moisture Barrier Bag (MBB). A Humidity Indicator Card (HIC) and drying desiccant are included inside the MBB. A MSL 3 label is attached to caution that the bag contains moisture sensitive devices.
- b. Calculated shelf life in a sealed bag: 12 months at <40°C and <90% room humidity.
- c. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must be mounted within go through reflow for board assembly within 168 hours of factory conditions <30°C/60% RH, or stored at <10% RH. If both of these conditions are not met, baking is required before board mounting.
- d. Before a device is removed from the PCB or module, the PCB or module must first be baked.
- e. Any unused devices after the MBB has been opened for more than 48 hours or not stored at <10% RH should be baked before any subsequent reflow and board assembly.
- f. If baking is required, devices should be baked for a minimum of 8 hours at 125°C.

3. Reference

Customers may refer to following IPC/JEDEC standards for more details:

- IPC/JEDEC J-STD-033 J-STD-033
- IPC/JEDEC J-STD-020A

Revision History

Revision	Date	Description of Change
00	2020-12-18	First Release